

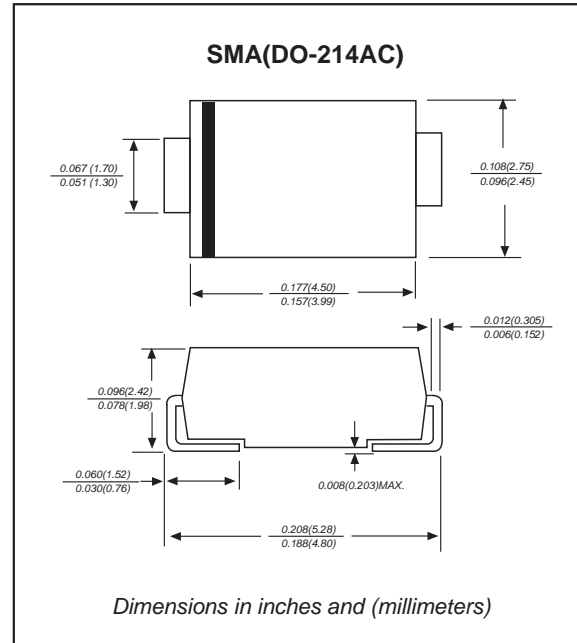
Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Super fast switching for high efficiency
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 250°C/10 seconds at terminals
- ◆ Glass passivated chip junction
- ◆ Compliant to RoHS Directive 2011/65/EU

Mechanical data

- ◆ **Case:** JEDEC DO-214AC molded plastic body
- ◆ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity:** Color band denotes cathode end
- ◆ **Mounting Position:** Any

Package outline

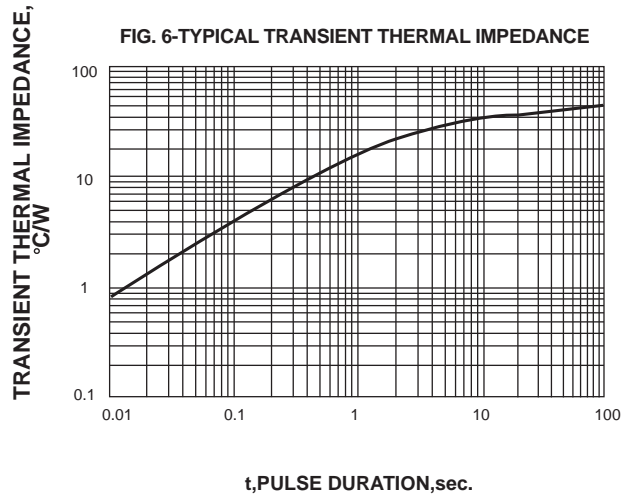
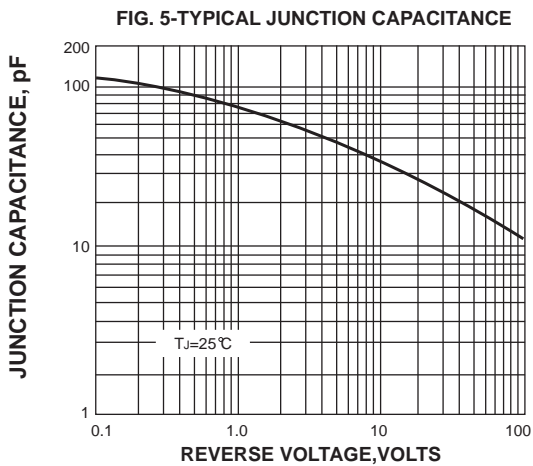
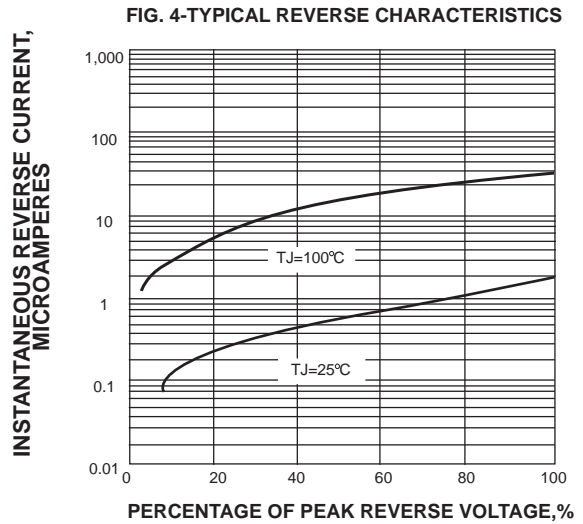
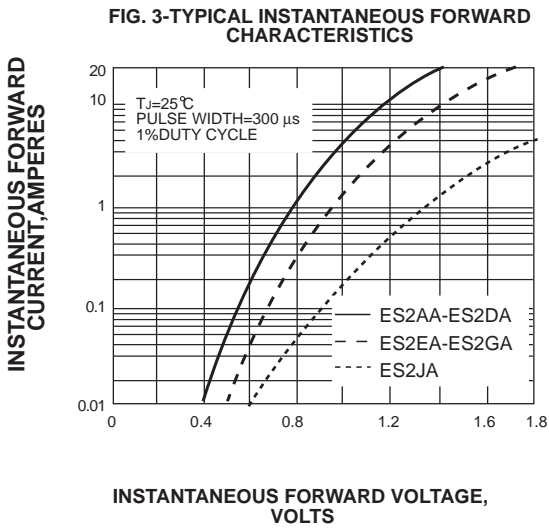
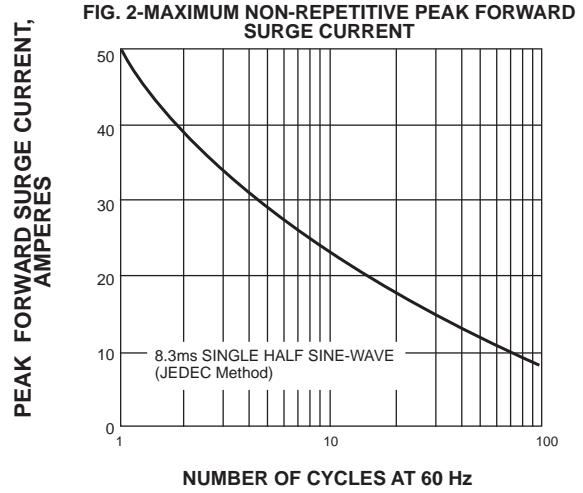
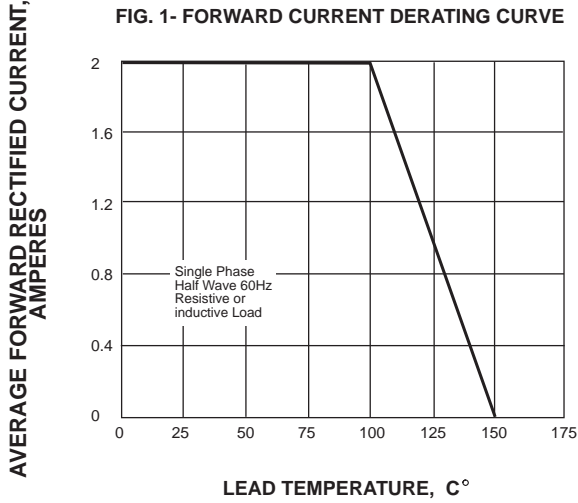


Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

	SYMBOLS	ES2AA	ES2BA	ES2CA	ES2DA	ES2EA	ES2GA	ES2JA	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	420	V
Maximum DC blocking voltage	V_{DC}	50	100	150	200	300	400	600	V
Maximum average forward rectified current at $T_L=75^\circ\text{C}$	$I_{(AV)}$	2.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	50.0							A
Maximum instantaneous forward voltage at 2.0A	V_F	0.95			1.25		1.7		V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=100^\circ\text{C}$	I_R	5.0 50.0							μA
Maximum reverse recovery time (NOTE 1)	t_{rr}	35							ns
Typical junction capacitance (NOTE 2)	C_J	40.0							pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	60.0							$^\circ\text{C/W}$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150							$^\circ\text{C}$

- Note:**
- 1.Reverse recovery condition $I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$
 - 2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 - 3.P.C.B. mounted with 2.0x2.0" (5.0x5.0cm) copper pad areas

Rating and characteristic curves



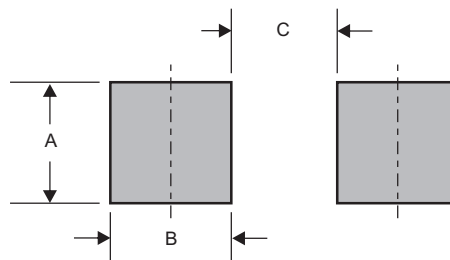
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
ES2AA	ES2A
ES2BA	ES2B
ES2CA	ES2C
ES2DA	ES2D
ES2EA	ES2E
ES2GA	ES2G
ES2JA	ES2J

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMA/DO-214AC	0.110 (2.80)	0.063 (1.60)	0.087 (2.20)

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes